

APKB3025SURKMGK

HYPER RED

MEGA GREEN

Features

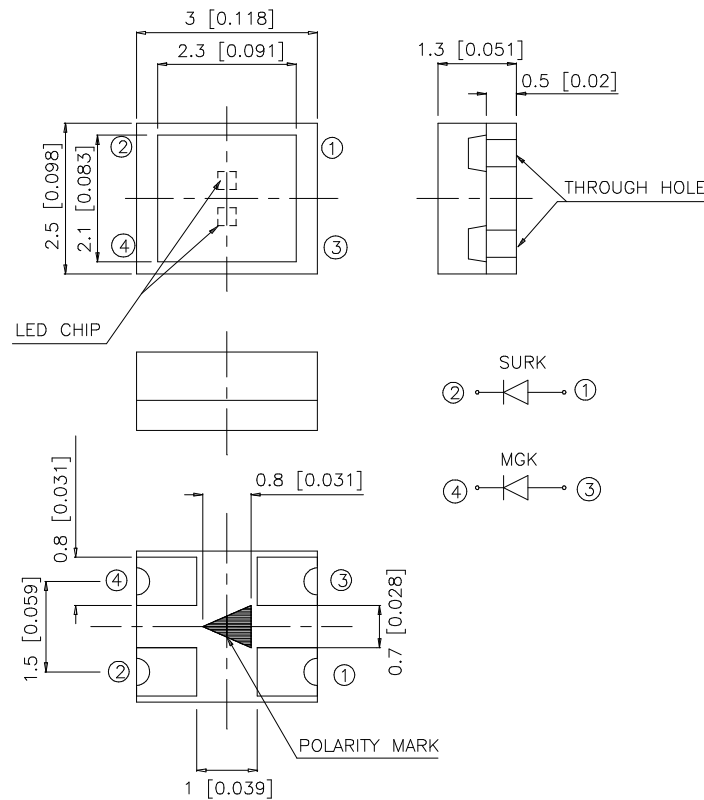
- 3.0mmx2.5mm SMT LED, 1.3mm THICKNESS.
- BI -COLOR, LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 2000PCS / REEL.

Description

The Hyper Red source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

The Mega Green source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.2 (0.008") unless otherwise noted.
3. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	2θ1/2
APKB3025SURKMGK	HYPER RED (InGaAlP)	WATER CLEAR	70	150	120°
	MEGA GREEN (InGaAlP)		10	50	

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at T_A=25°C

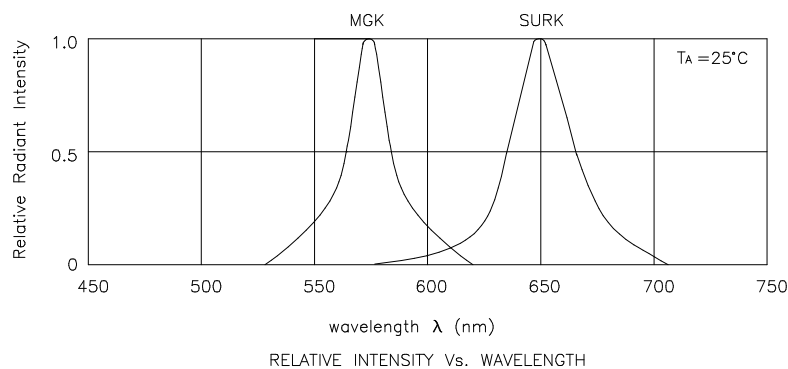
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	Hyper Red Mega Green	650 574		nm	I _F =20mA
λ _D	Dominate Wavelength	Hyper Red Mega Green	635 570		nm	I _F =20mA
Δλ _{1/2}	Spectral Line Half-width	Hyper Red Mega Green	28 20		nm	I _F =20mA
C	Capacitance	Hyper Red Mega Green	35 15		pF	V _F =0V; f=1MHz
V _F	Forward Voltage	Hyper Red Mega Green	1.95 2.1	2.5 2.5	V	I _F =20mA
I _R	Reverse Current	All		10	uA	V _R = 5V

Absolute Maximum Ratings at T_A=25°C

Parameter	Hyper Red	Mega Green	Units
Power dissipation	170	105	mW
DC Forward Current	30	30	mA
Peak Forward Current [1]	185	150	mA
Reverse Voltage	5	5	V
Operating/Storage Temperature	-40°C To +85°C		

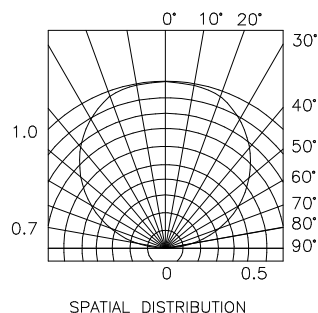
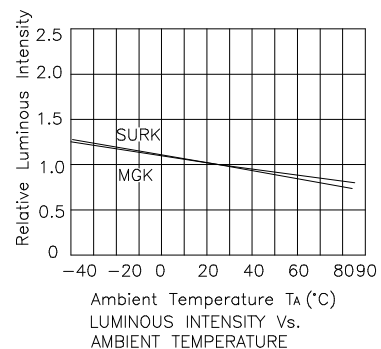
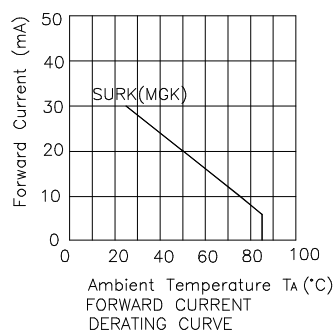
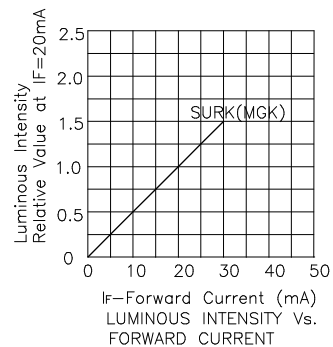
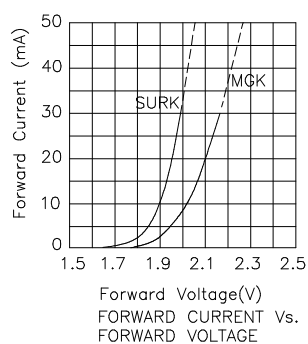
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



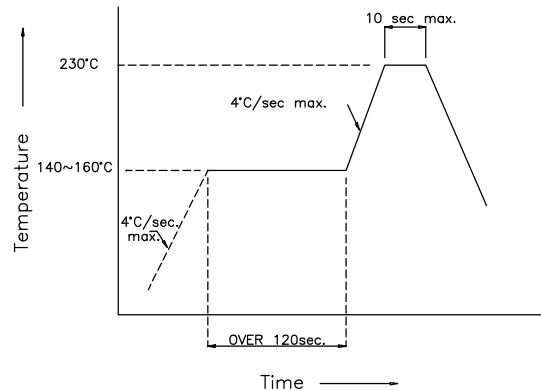
Hyper Red / Mega Green

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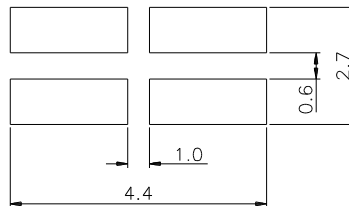


APKB3025SURKMGK SMT Reflow Soldering Instruction

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)

